


NOTES

- MATERIALS:**
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.
- FINISH:**
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICRONS (2.5um-7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um-2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH:** BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
- PACKAGE CONFORMS TO JEDEC MO-220**

PROPRIETARY AND CONFIDENTIAL
THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF QPTECHNOLOGIES. ANY REPRODUCTION, IN PART, OR AS A WHOLE WITHOUT THE WRITTEN PERMISSION OF QPTECHNOLOGIES IS PROHIBITED.

		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .X = ±0.76 .XX: ±0.25 .XXX = ±0.13 .XXXX = ±0.01		DRAWN	D. Abbe	8/1/11	 QPTECHNOLOGIES <small>A DIVISION OF FROMEX INDUSTRIES QPTECHNOLOGIES.COM</small>		
				CHECKED	S. Swen	8/1/11		TITLE: QP-QFN24-4MM-0.50MM	
				ENG APPR.	S. Swen	8/1/11			
				COMMENTS:			SIZE B	DWG. NO. 500378	REV A
NEXT ASSY		USED ON		MATERIAL		SEE NOTE 1		SCALE: 12:1	
APPLICATION		DO NOT SCALE DRAWING		FINISH		SEE NOTE 2		WEIGHT:	
								SHEET 1 OF 1	

